



**THE DATASHEET OF  
PCA9554ARGVR**



# PCA9554A Remote 8-Bit I<sup>2</sup>C and SMBus I/O Expander With Interrupt Output and Configuration Registers

## 1 Features

- I<sup>2</sup>C to Parallel Port Expander
- Open-Drain Active-Low Interrupt Output
- Operating Power-Supply Voltage Range of 2.3 V to 5.5 V
- 5-V Tolerant I/Os
- 400-kHz Fast I<sup>2</sup>C Bus
- Three Hardware Address Pins Allow up to Eight Devices on the I<sup>2</sup>C/SMBus
- Input/Output Configuration Register
- Polarity Inversion Register
- Internal Power-On Reset
- Power-Up With All Channels Configured as Inputs
- No Glitch on Power Up
- Latched Outputs With High-Current Drive Maximum Capability for Directly Driving LEDs
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## 2 Description

This 8-bit I/O expander for the two-line bidirectional bus (I<sup>2</sup>C) is designed for 2.3-V to 5.5-V V<sub>CC</sub> operation. It provides general-purpose remote I/O expansion for most microcontroller families via the I<sup>2</sup>C interface [serial clock (SCL), serial data (SDA)].

The PCA9554A consists of one 8-bit Configuration (input or output selection), Input, Output, and Polarity Inversion (active high or active low) registers. At power on, the I/Os are configured as inputs with a weak pullup to V<sub>CC</sub>. However, the system master can enable the I/Os as either inputs or outputs by writing to the I/O configuration bits. The data for each input or output is kept in the corresponding Input or Output register. The polarity of the Input Port register can be inverted with the Polarity Inversion register. All registers can be read by the system master.

The system master can reset the PCA9554A in the event of a timeout or other improper operation by utilizing the power-on reset feature, which puts the registers in their default state and initializes the I<sup>2</sup>C/SMBus state machine.

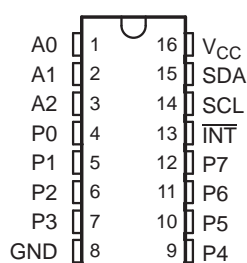
The PCA9554A open-drain interrupt ( $\overline{\text{INT}}$ ) output is activated when any input state differs from its corresponding Input Port register state and is used to indicate to the system master that an input state has changed.

### Device Information<sup>(1)</sup>

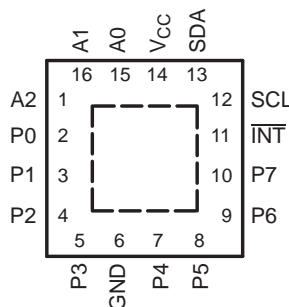
PART NUMBER	PACKAGE	BODY SIZE (NOM)
PCA9554A	SSOP (16)	6.20 mm x 5.30 mm
	VQFN (16)	4.00 mm x 4.00 mm
	QFN (16)	3.00 mm x 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

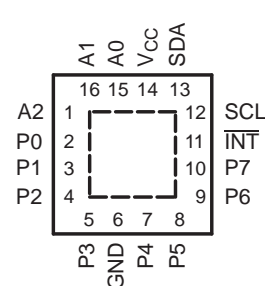
DB, DBQ, DGV, DW,  
OR PW PACKAGE  
(TOP VIEW)



RGV PACKAGE  
(TOP VIEW)



RGT PACKAGE  
(TOP VIEW)



## Table of Contents

<b>1</b>	<b>Features</b> .....	<b>1</b>	<b>8</b>	<b>Detailed Description</b> .....	<b>13</b>
<b>2</b>	<b>Description</b> .....	<b>1</b>	8.1	Functional Block Diagram .....	13
<b>3</b>	<b>Revision History</b> .....	<b>2</b>	8.2	Device Functional Modes.....	14
<b>4</b>	<b>Description (Continued)</b> .....	<b>3</b>	8.3	Programming.....	15
<b>5</b>	<b>Pin Configuration And Functions</b> .....	<b>3</b>	<b>9</b>	<b>Application And Implementation</b> .....	<b>21</b>
<b>6</b>	<b>Specifications</b> .....	<b>4</b>	9.1	Typical Application .....	21
6.1	Absolute Maximum Ratings .....	4	<b>10</b>	<b>Power Supply Recommendations</b> .....	<b>23</b>
6.2	Handling Ratings.....	4	10.1	Power-On Reset Errata.....	23
6.3	Recommended Operating Conditions.....	4	<b>11</b>	<b>Device and Documentation Support</b> .....	<b>23</b>
6.4	Electrical Characteristics.....	5	11.1	Trademarks .....	23
6.5	I <sup>2</sup> C Interface Timing Requirements.....	6	11.2	Electrostatic Discharge Caution.....	23
6.6	Switching Characteristics .....	6	11.3	Glossary .....	23
6.7	Typical Characteristics .....	7	<b>12</b>	<b>Mechanical, Packaging, and Orderable Information</b> .....	<b>23</b>
<b>7</b>	<b>Parameter Measurement Information</b> .....	<b>10</b>			

## 3 Revision History

Changes from Revision D (August 2008) to Revision E	Page
• Added Interrupt Errata section. ....	15
• Added Power-On Reset Errata section. ....	23

## 4 Description (Continued)

$\overline{\text{INT}}$  can be connected to the interrupt input of a microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the I<sup>2</sup>C bus. Thus, the PCA9554A can remain a simple slave device.

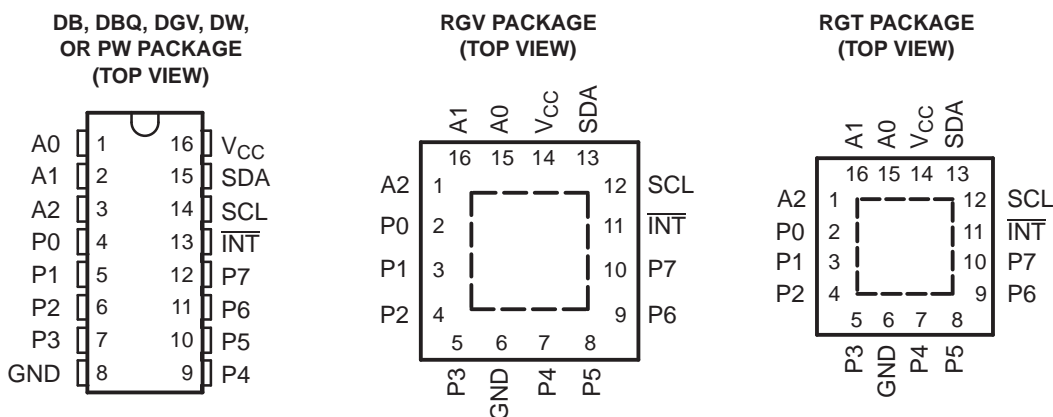
The device's outputs (latched) have high-current drive capability for directly driving LEDs and low current consumption.

Three hardware pins (A0, A1, and A2) are used to program and vary the fixed I<sup>2</sup>C address and allow up to eight devices to share the same I<sup>2</sup>C bus or SMBus.

The PCA9554A is pin-to-pin and I<sup>2</sup>C address compatible with the PCF8574A. However, software changes are required, due to the enhancements in the PCA9554A over the PCF8574A.

The PCA9554A and PCA9554 are identical except for their fixed I<sup>2</sup>C address. This allows for up to 16 of these devices (8 of each) on the same I<sup>2</sup>C/SMBus.

## 5 Pin Configuration And Functions



### Pin Functions

NAME	PIN		DESCRIPTION
	QSOP (DBQ), SOIC (DW), SSOP (DB), TSSOP (PW), AND TVSOP (DGV)	QFN (RGT AND RGV)	
A0	1	15	Address input. Connect directly to V <sub>CC</sub> or ground.
A1	2	16	Address input. Connect directly to V <sub>CC</sub> or ground.
A2	3	1	Address input. Connect directly to V <sub>CC</sub> or ground.
P0	4	2	P-port input/output. Push-pull design structure.
P1	5	3	P-port input/output. Push-pull design structure.
P2	6	4	P-port input/output. Push-pull design structure.
P3	7	5	P-port input/output. Push-pull design structure.
GND	8	6	Ground
P4	9	7	P-port input/output. Push-pull design structure.
P5	10	8	P-port input/output. Push-pull design structure.
P6	11	9	P-port input/output. Push-pull design structure.
P7	12	10	P-port input/output. Push-pull design structure.
$\overline{\text{INT}}$	13	11	Interrupt output. Connect to V <sub>CC</sub> through a pullup resistor.
SCL	14	12	Serial clock bus. Connect to V <sub>CC</sub> through a pullup resistor.
SDA	15	13	Serial data bus. Connect to V <sub>CC</sub> through a pullup resistor.
V <sub>CC</sub>	16	14	Supply voltage

## 6 Specifications

### 6.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	6	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	-0.5	6	V
V <sub>O</sub>	Output voltage range <sup>(2)</sup>	-0.5	6	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-20	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	-20	mA
I <sub>IOK</sub>	Input/output clamp current	V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub>	±20	mA
I <sub>OL</sub>	Continuous output low current	V <sub>O</sub> = 0 to V <sub>CC</sub>	50	mA
I <sub>OH</sub>	Continuous output high current	V <sub>O</sub> = 0 to V <sub>CC</sub>	-50	mA
I <sub>CC</sub>	Continuous current through GND		-250	mA
	Continuous current through V <sub>CC</sub>		160	
θ <sub>JA</sub>	Package thermal impedance <sup>(3)</sup>	DB package	82	°C/W
		DBQ package	90	
		DGV package	120	
		DW package	57	
		PW package	108	
		RGT package	TBD	
		RGV package	51	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

### 6.2 Handling Ratings

		MIN	MAX	UNIT	
T <sub>stg</sub>	Storage temperature range	-65	150	°C	
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	0	2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	0	1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage	2.3	5.5	V	
V <sub>IH</sub>	High-level input voltage	SCL, SDA	0.7 × V <sub>CC</sub>	5.5	V
		A2–A0, P7–P0	2	5.5	
V <sub>IL</sub>	Low-level input voltage	SCL, SDA	-0.5	0.3 × V <sub>CC</sub>	V
		A2–A0, P7–P0	-0.5	0.8	
I <sub>OH</sub>	High-level output current	P7–P0	-10	mA	
I <sub>OL</sub>	Low-level output current	P7–P0	25	mA	
T <sub>A</sub>	Operating free-air temperature	-40	85	°C	

## 6.4 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>IK</sub>	Input diode clamp voltage	I <sub>I</sub> = -18 mA	2.3 V to 5.5 V	-1.2			V
V <sub>POR</sub>	Power-on reset voltage	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	V <sub>POR</sub>		1.5	1.65	V
V <sub>OH</sub>	P-port high-level output voltage <sup>(2)</sup>	I <sub>OH</sub> = -8 mA	2.3 V	1.8			V
			3 V	2.6			
			4.5 V	3.1			
			4.75 V	4.1			
		I <sub>OH</sub> = -10 mA	2.3 V	1.7			
			3 V	2.5			
			4.5 V	3			
			4.75 V	4			
I <sub>OL</sub>	SDA	V <sub>OL</sub> = 0.4 V	2.3 V to 5.5 V	3	8		mA
	P port <sup>(3)</sup>	V <sub>OL</sub> = 0.5 V	2.3 V	8	10		
			3 V	8	14		
			4.5 V	8	17		
			4.75 V	8	35		
		V <sub>OL</sub> = 0.7 V	2.3 V	10	13		
			3 V	10	19		
			4.5 V	10	24		
			4.75 V	10	45		
	INT	V <sub>OL</sub> = 0.4 V	2.3 V to 5.5 V	3	10		
I <sub>I</sub>	SCL, SDA	V <sub>I</sub> = V <sub>CC</sub> or GND	2.3 V to 5.5 V			±1	μA
	A2–A0					±1	
I <sub>IH</sub>	P port	V <sub>I</sub> = V <sub>CC</sub>	2.3 V to 5.5 V			1	μA
I <sub>IL</sub>	P port	V <sub>I</sub> = GND	2.3 V to 5.5 V			-100	μA
I <sub>CC</sub>	Operating mode	V <sub>I</sub> = V <sub>CC</sub> , I <sub>O</sub> = 0, I/O = inputs, f <sub>scl</sub> = 400 kHz, No load	5.5 V		104	175	μA
			3.6 V		50	90	
			2.7 V		20	65	
			5.5 V		60	150	
			3.6 V		15	40	
			2.7 V		8	20	
	Standby mode	V <sub>I</sub> = V <sub>CC</sub> , I <sub>O</sub> = 0, I/O = inputs, f <sub>scl</sub> = 100 kHz, No load	5.5 V		450	700	
			3.6 V		300	600	
			2.7 V		225	500	
			5.5 V		0.25	1	
			3.6 V		0.2	0.9	
			2.7 V		0.1	0.8	
ΔI <sub>CC</sub>	Additional current in standby mode	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.3 V to 5.5 V			1.5	mA
		Every LED I/O at V <sub>I</sub> = 4.3 V; f <sub>scl</sub> = 0 kHz	5.5 V			1	
C <sub>I</sub>	SCL	V <sub>I</sub> = V <sub>CC</sub> or GND	2.3 V to 5.5 V		4	5	pF
C <sub>io</sub>	SDA	V <sub>IO</sub> = V <sub>CC</sub> or GND	2.3 V to 5.5 V		5.5	6.5	pF
	P port				8	9.5	

(1) All values are at nominal supply voltage (2.5-V, 3.3-V, or 5-V V<sub>CC</sub>) and T<sub>A</sub> = 25°C.

(2) The total current sourced by all I/Os must be limited to 85 mA.

(3) Each I/O must be externally limited to a maximum of 25 mA, and the P port (P0 to P7) must be limited to a maximum current of 200 mA.

## 6.5 I<sup>2</sup>C Interface Timing Requirements

 over operating free-air temperature range (unless otherwise noted) (see [Figure 14](#))

	STANDARD MODE I <sup>2</sup> C BUS		FAST MODE I <sup>2</sup> C BUS		UNIT	
	MIN	MAX	MIN	MAX		
t <sub>scl</sub> I <sup>2</sup> C clock frequency	0	100	0	400	kHz	
t <sub>sch</sub> I <sup>2</sup> C clock high time	4		0.6		μs	
t <sub>scl</sub> I <sup>2</sup> C clock low time	4.7		1.3		μs	
t <sub>sp</sub> I <sup>2</sup> C spike time		50		50	ns	
t <sub>sds</sub> I <sup>2</sup> C serial-data setup time	250		100		ns	
t <sub>sdh</sub> I <sup>2</sup> C serial-data hold time	0		0		ns	
t <sub>icr</sub> I <sup>2</sup> C input rise time		1000	20 + 0.1C <sub>b</sub> <sup>(1)</sup>	300	ns	
t <sub>icf</sub> I <sup>2</sup> C input fall time		300	20 + 0.1C <sub>b</sub> <sup>(1)</sup>	300	ns	
t <sub>ocf</sub> I <sup>2</sup> C output fall time	10-pF to 400-pF bus	300	20 + 0.1C <sub>b</sub> <sup>(1)</sup>	300	ns	
t <sub>buf</sub> I <sup>2</sup> C bus free time between Stop and Start		4.7		1.3	μs	
t <sub>sts</sub> I <sup>2</sup> C Start or repeated Start condition setup		4.7		0.6	μs	
t <sub>sth</sub> I <sup>2</sup> C Start or repeated Start condition hold		4		0.6	μs	
t <sub>sps</sub> I <sup>2</sup> C Stop condition setup		4		0.6	μs	
t <sub>vd(data)</sub> Valid data time	SCL low to SDA output valid	300		50	ns	
t <sub>vd(ack)</sub> Valid data time of ACK condition	ACK signal from SCL low to SDA (out) low	0.3	3.45	0.1	0.9	μs
C <sub>b</sub> I <sup>2</sup> C bus capacitive load			400		400	ns

 (1) C<sub>b</sub> = Total capacitive load of one bus in pF

## 6.6 Switching Characteristics

 over operating free-air temperature range (unless otherwise noted) (see [Figure 15](#) and [Figure 16](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	STANDARD MODE I <sup>2</sup> C BUS		FAST MODE I <sup>2</sup> C BUS		UNIT
			MIN	MAX	MIN	MAX	
t <sub>iv</sub> Interrupt valid time	P port	$\overline{\text{INT}}$		4		4	μs
t <sub>ir</sub> Interrupt reset delay time	SCL	$\overline{\text{INT}}$		4		4	μs
t <sub>pV</sub> Output data valid	SCL	P7–P0		200		200	ns
t <sub>ps</sub> Input data setup time	P port	SCL	100		100		ns
t <sub>ph</sub> Input data hold time	P port	SCL	1		1		μs

## 6.7 Typical Characteristics

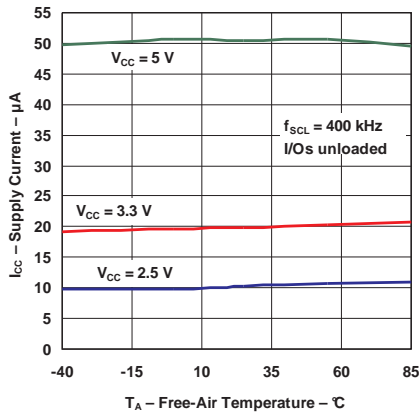


Figure 1. Supply Current vs Temperature

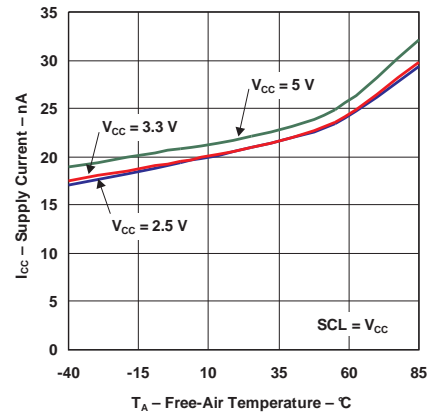


Figure 2. Quiescent Supply Current vs Temperature

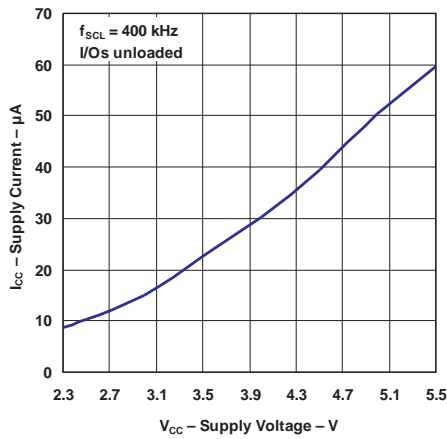


Figure 3. Supply Current vs Supply Voltage

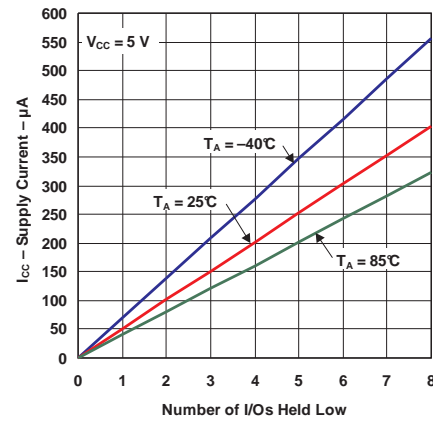


Figure 4. Supply Current vs Number Of I/Os Held Low

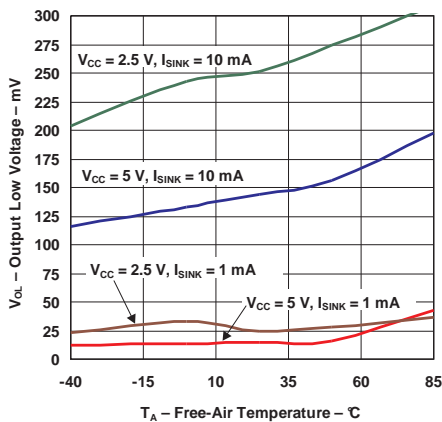


Figure 5. I/O Output Low Voltage vs Temperature

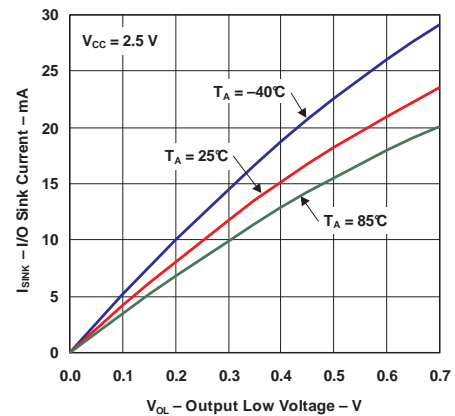


Figure 6. I/O Sink Current vs Output Low Voltage

Typical Characteristics (continued)

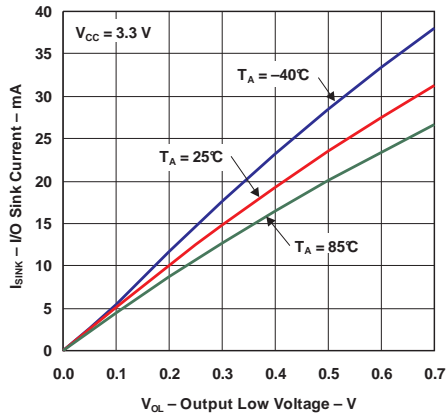


Figure 7. I/O Sink Current vs Output Low Voltage

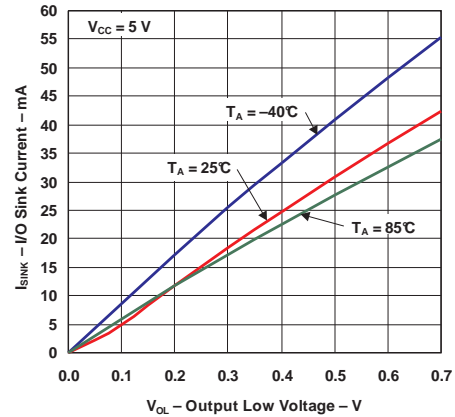


Figure 8. I/O Sink Current vs Output Low Voltage

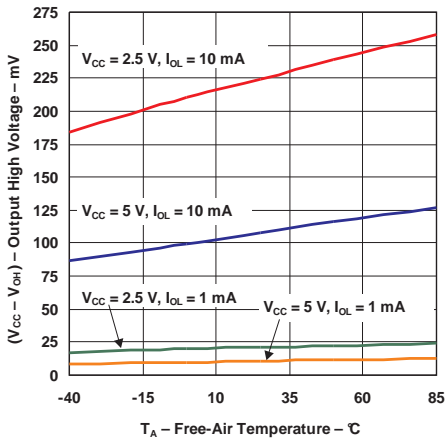


Figure 9. I/O Output High Voltage vs Temperature

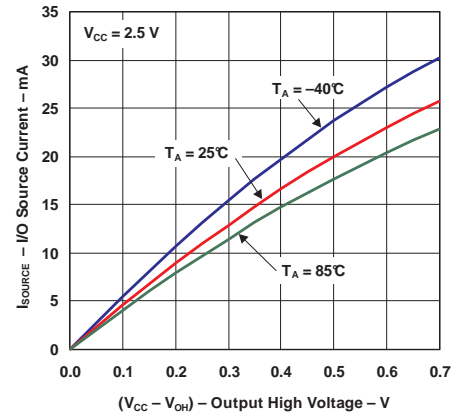


Figure 10. I/O Source Current vs Output High Voltage

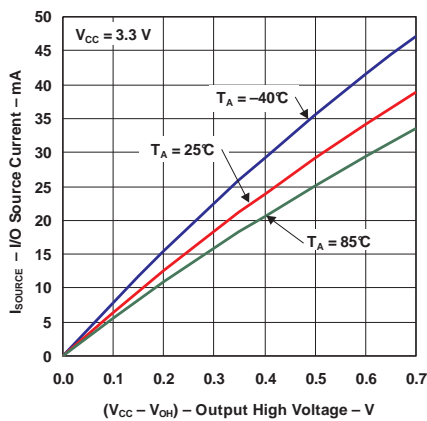


Figure 11. I/O Source Current vs Output High Voltage

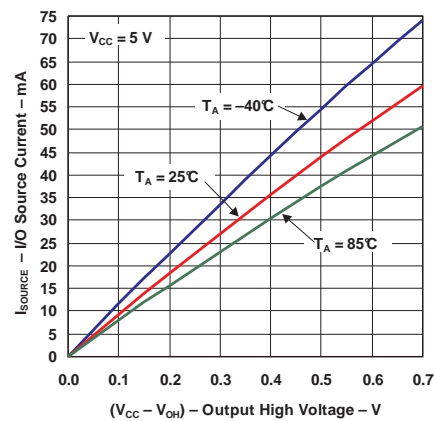


Figure 12. I/O Source Current vs Output High Voltage

Typical Characteristics (continued)

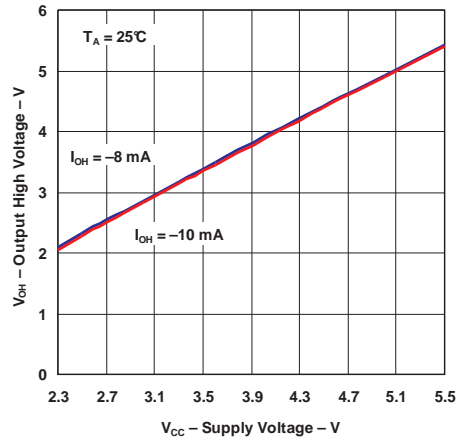
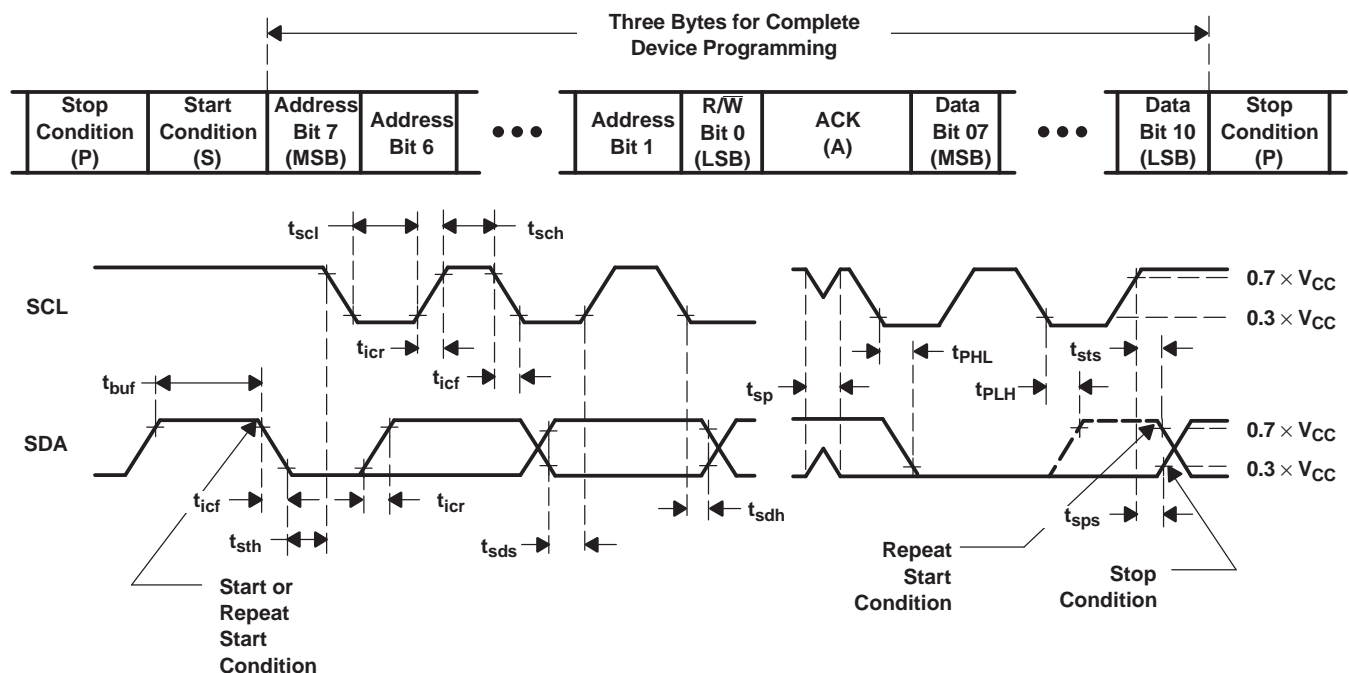


Figure 13. Output High Voltage vs Supply Voltage

## 7 Parameter Measurement Information



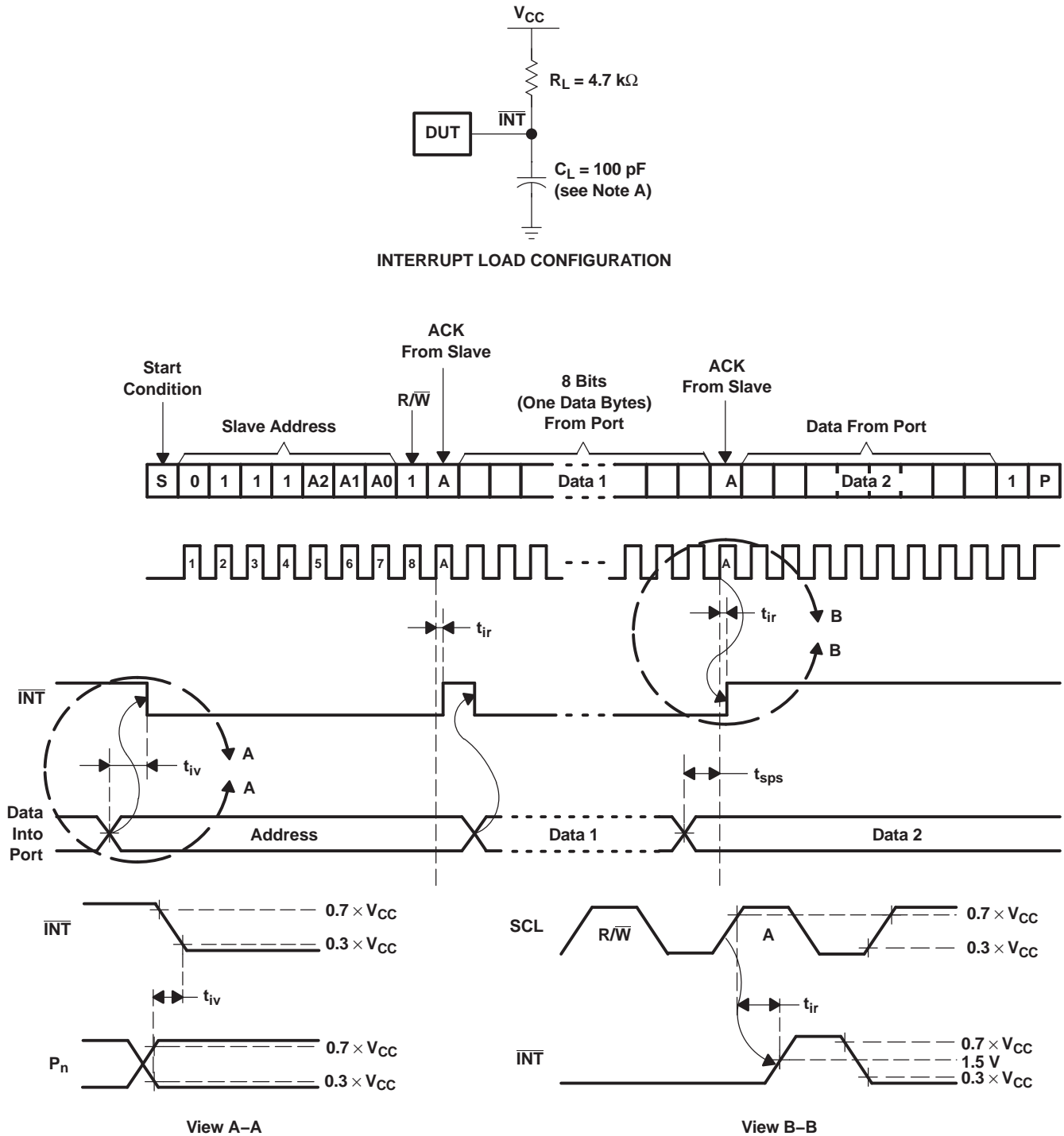
VOLTAGE WAVEFORMS

BYTE	DESCRIPTION
1	I <sup>2</sup> C address
2, 3	P-port data

- A.  $C_L$  includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r/t_f \leq 30$  ns.
- C. All parameters and waveforms are not applicable to all devices.

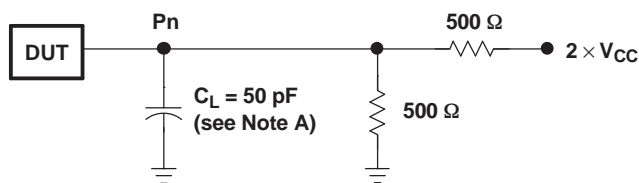
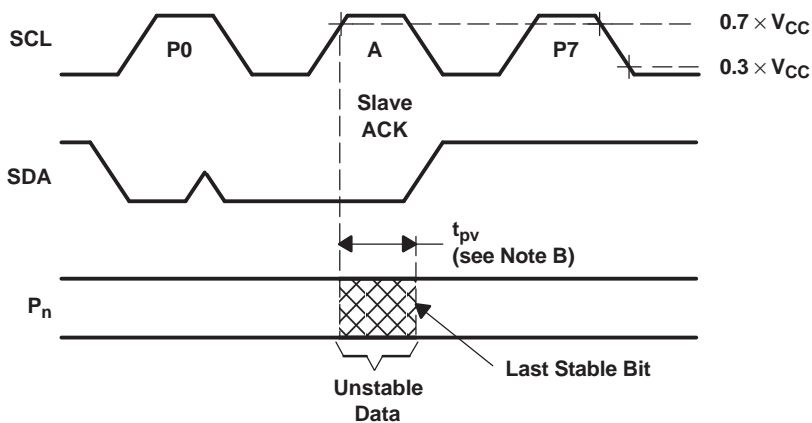
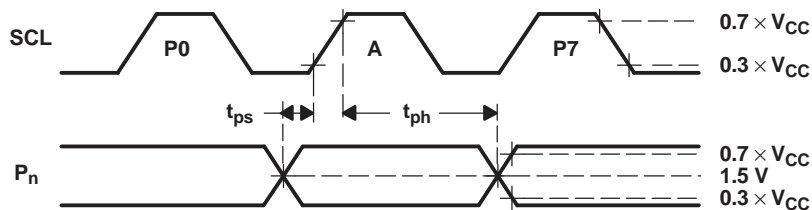
**Figure 14. I<sup>2</sup>C Interface Load Circuit And Voltage Waveforms**

Parameter Measurement Information (continued)



- A.  $C_L$  includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_r/t_f \leq 30$  ns.
- C. All parameters and waveforms are not applicable to all devices.

Figure 15. Interrupt Load Circuit And Voltage Waveforms

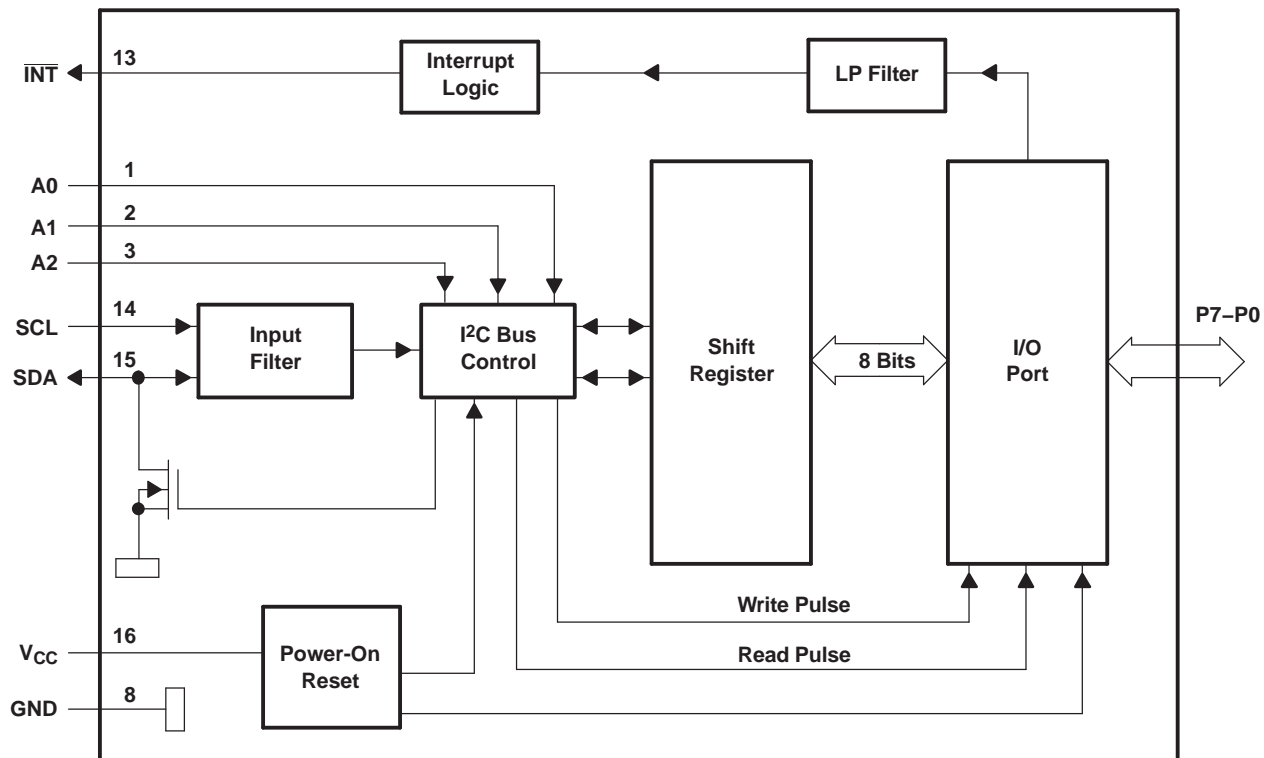
**Parameter Measurement Information (continued)**

**P-PORT LOAD CONFIGURATION**

**WRITE MODE ( $R/\bar{W} = 0$ )**

**READ MODE ( $R/\bar{W} = 1$ )**

- A.  $C_L$  includes probe and jig capacitance.
- B.  $t_{pv}$  is measured from  $0.7 \times V_{CC}$  on SCL to 50% I/O pin output.
- C. All inputs are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $t_r/t_f \leq 30$  ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

**Figure 16. P-Port Load Circuit And Voltage Waveforms**

## 8 Detailed Description

### 8.1 Functional Block Diagram



- A. Pin numbers shown are for the DB, DBQ, DGV, DW, or PW package.
- B. All I/Os are set to inputs at reset.

Figure 17. Logic Diagram



## Device Functional Modes (continued)

Interrupts that occur during the ACK or NACK clock pulse can be lost (or be very short) due to the resetting of the interrupt during this pulse. Each change of the I/Os after resetting is detected and is transmitted as  $\overline{\text{INT}}$ . Writing to another device does not affect the interrupt circuit, and a pin configured as an output cannot cause an interrupt. Changing an I/O from an output to an input may cause a false interrupt to occur, if the state of the pin does not match the contents of the Input Port register. Because each 8-pin port is read independently, the interrupt caused by port 0 is not cleared by a read of port 1 or vice versa.

The  $\overline{\text{INT}}$  output has an open-drain structure and requires pull-up resistor to  $V_{CC}$ .

### 8.2.3.1 Interrupt Errata

#### Description

The INT will be improperly de-asserted if the following two conditions occur:

1. The last I<sup>2</sup>C command byte (register pointer) written to the device was 00h.

---

#### NOTE

This generally means the last operation with the device was a Read of the input register. However, the command byte may have been written with 00h without ever going on to read the input register. After reading from the device, if no other command byte written, it will remain 00h.

2. Any other slave device on the I<sup>2</sup>C bus acknowledges an address byte with the R/W bit set high

#### System Impact

Can cause improper interrupt handling as the Master will see the interrupt as being cleared.

#### System Workaround

Minor software change: User must change command byte to something besides 00h after a Read operation to the PCA9554A device or before reading from another slave device.

---

#### NOTE

Software change will be compatible with other versions (competition and TI redesigns) of this device.

---

## 8.3 Programming

### 8.3.1 I<sup>2</sup>C Interface

The bidirectional I<sup>2</sup>C bus consists of the serial clock (SCL) and serial data (SDA) lines. Both lines must be connected to a positive supply through a pullup resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

I<sup>2</sup>C communication with this device is initiated by a master sending a Start condition, a high-to-low transition on the SDA input/output while the SCL input is high (see [Figure 19](#)). After the Start condition, the device address byte is sent, most significant bit (MSB) first, including the data direction bit (R/W).

After receiving the valid address byte, this device responds with an acknowledge (ACK), a low on the SDA input/output during the high of the ACK-related clock pulse. The address inputs (A0–A2) of the slave device must not be changed between the Start and Stop conditions.

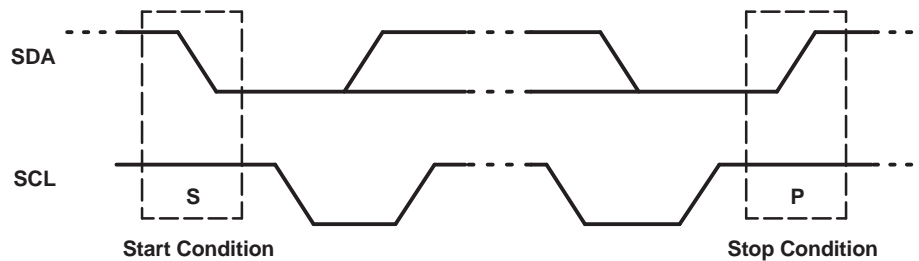
On the I<sup>2</sup>C bus, only one data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the high pulse of the clock period, as changes in the data line at this time are interpreted as control commands (Start or Stop) (see [Figure 20](#)).

A Stop condition, a low-to-high transition on the SDA input/output while the SCL input is high, is sent by the master (see [Figure 19](#)).

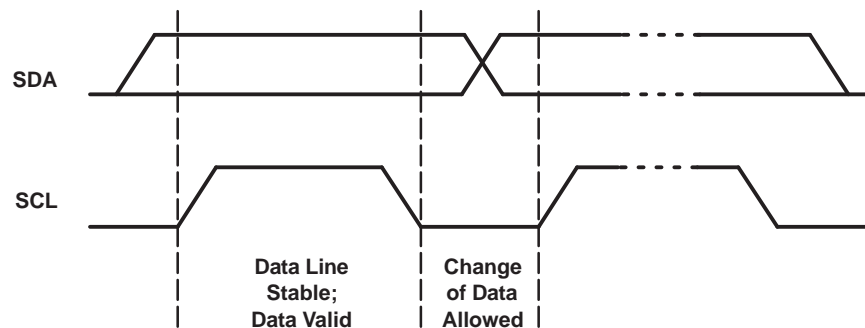
## Programming (continued)

Any number of data bytes can be transferred from the transmitter to receiver between the Start and Stop conditions. Each byte of eight bits is followed by one ACK bit. The transmitter must release the SDA line before the receiver can send an ACK bit. The device that acknowledges must pull down the SDA line during the ACK clock pulse so that the SDA line is stable low during the high pulse of the ACK-related clock period (see [Figure 21](#)). When a slave receiver is addressed, it must generate an ACK after each byte is received. Similarly, the master must generate an ACK after each byte that it receives from the slave transmitter. Setup and hold times must be met to ensure proper operation.

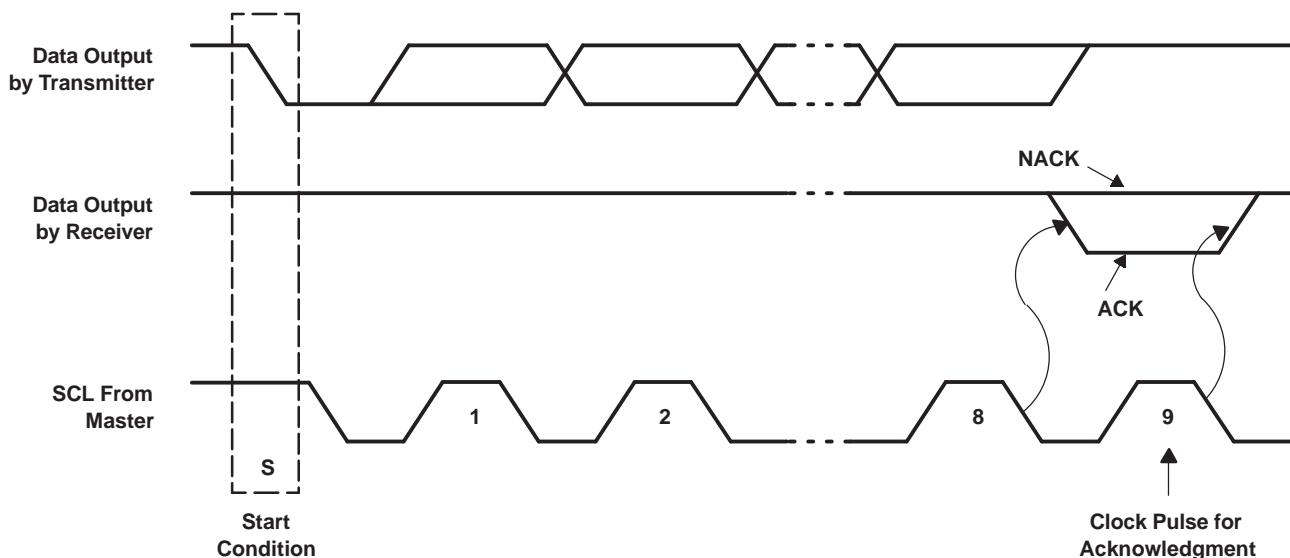
A master receiver will signal an end of data to the slave transmitter by not generating an acknowledge (NACK) after the last byte has been clocked out of the slave. This is done by the master receiver by holding the SDA line high. In this event, the transmitter must release the data line to enable the master to generate a Stop condition.



**Figure 19. Definition Of Start And Stop Conditions**



**Figure 20. Bit Transfer**



**Figure 21. Acknowledgment On The I<sup>2</sup>C Bus**

## Programming (continued)

### 8.3.2 Register Map

Table 1. Interface Definition

BYTE	BIT							
	7 (MSB)	6	5	4	3	2	1	0 (LSB)
I <sup>2</sup> C slave address	L	H	H	H	A2	A1	A0	R/ $\bar{W}$
Px I/O data bus	P7	P6	P5	P4	P3	P2	P1	P0

#### 8.3.2.1 Device Address

Figure 22 shows the address byte for the PCA9554A.

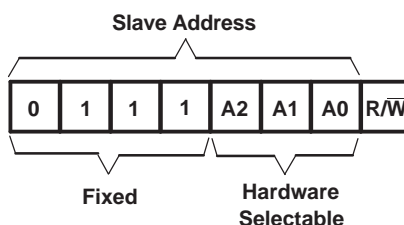


Figure 22. Pca9554a Address

Table 2. Address Reference

INPUTS			I <sup>2</sup> C BUS SLAVE ADDRESS
A2	A1	A0	
L	L	L	56 (decimal), 38 (hexadecimal)
L	L	H	57 (decimal), 39 (hexadecimal)
L	H	L	58 (decimal), 3A (hexadecimal)
L	H	H	59 (decimal), 3B (hexadecimal)
H	L	L	60 (decimal), 3C (hexadecimal)
H	L	H	61 (decimal), 3D (hexadecimal)
H	H	L	62 (decimal), 3E (hexadecimal)
H	H	H	63 (decimal), 3F (hexadecimal)

The last bit of the slave address defines the operation (read or write) to be performed. When it is high (1), a read is selected. A low (0) selects a write operation.

#### 8.3.2.2 Control Register And Command Byte

Following the successful acknowledgment of the address byte, the bus master sends a command byte that is stored in the control register in the PCA9554A. Two bits of this command byte state the operation (read or write) and the internal register (input, output, polarity inversion or configuration) that will be affected. This register can be written or read through the I<sup>2</sup>C bus. The command byte is sent only during a write transmission.

Once a command byte has been sent, the register that was addressed continues to be accessed by reads until a new command byte has been sent.

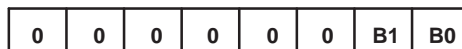


Figure 23. Control Register Bits

**Table 3. Command Byte**

CONTROL REGISTER BITS		COMMAND BYTE (HEX)	REGISTER	PROTOCOL	POWER-UP DEFAULT
B1	B0				
0	0	0x00	Input Port	Read byte	XXXX XXXX
0	1	0x01	Output Port	Read/write byte	1111 1111
1	0	0x02	Polarity Inversion	Read/write byte	0000 0000
1	1	0x03	Configuration	Read/write byte	1111 1111

### 8.3.2.3 Register Descriptions

The Input Port register (register 0) reflects the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by the Configuration register. It only acts on read operation. Writes to these registers have no effect. The default value, X, is determined by the externally applied logic level.

Before a read operation, a write transmission is sent with the command byte to let the I<sup>2</sup>C device know that the Input Port register will be accessed next.

**Table 4. Register 0 (Input Port Register)**

BIT	I7	I6	I5	I4	I3	I2	I1	I0
DEFAULT	X	X	X	X	X	X	X	X

The Output Port register (register 1) shows the outgoing logic levels of the pins defined as outputs by the Configuration register. Bit values in this register have no effect on pins defined as inputs. In turn, reads from this register reflect the value that is in the flip-flop controlling the output selection, not the actual pin value.

**Table 5. Register 1 (Output Port Register)**

BIT	O7	O6	O5	O4	O3	O2	O1	O0
DEFAULT	1	1	1	1	1	1	1	1

The Polarity Inversion register (register 2) allows polarity inversion of pins defined as inputs by the Configuration register. If a bit in this register is set (written with 1), the corresponding port pin polarity is inverted. If a bit in this register is cleared (written with a 0), the corresponding port pin original polarity is retained.

**Table 6. Register 2 (Polarity Inversion Register)**

BIT	N7	N6	N5	N4	N3	N2	N1	N0
DEFAULT	0	0	0	0	0	0	0	0

The Configuration register (register 3) configures the directions of the I/O pins. If a bit in this register is set to 1, the corresponding port pin is enabled as an input with high impedance output driver. If a bit in this register is cleared to 0, the corresponding port pin is enabled as an output.

**Table 7. Register 3 (Configuration Register)**

BIT	C7	C6	C5	C4	C3	C2	C1	C0
DEFAULT	1	1	1	1	1	1	1	1

### 8.3.2.4 Bus Transactions

Data is exchanged between the master and PCA9554A through write and read commands.

8.3.2.4.1 Writes

Data is transmitted to the PCA9554A by sending the device address and setting the least-significant bit to a logic 0 (see Figure 22 for device address). The command byte is sent after the address and determines which register receives the data that follows the command byte (see Figure 24 and Figure 25). There is no limitation on the number of data bytes sent in one write transmission.

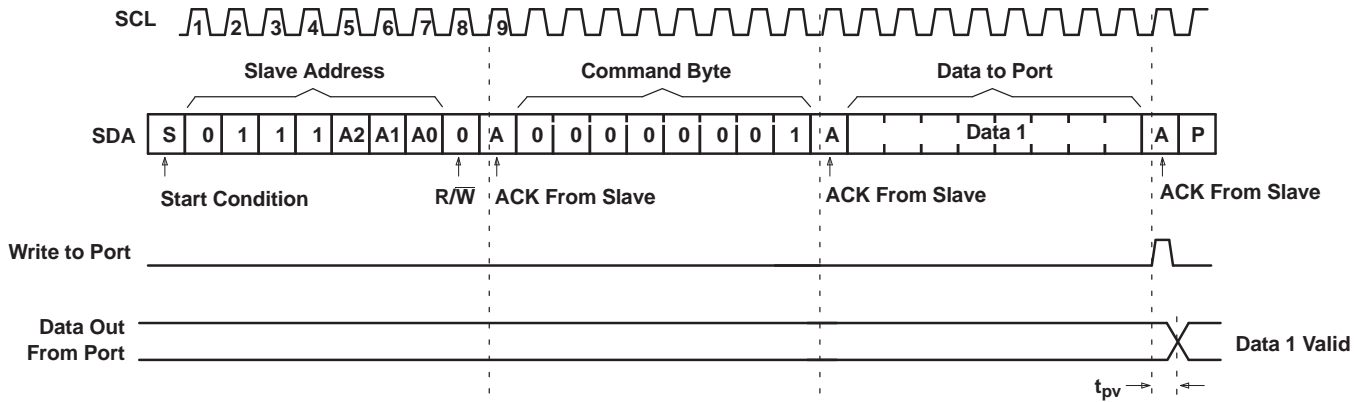


Figure 24. Write To Output Port Register

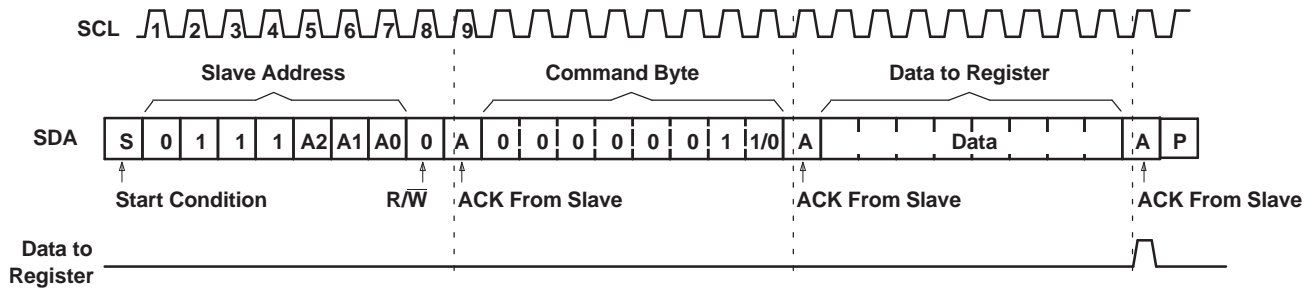
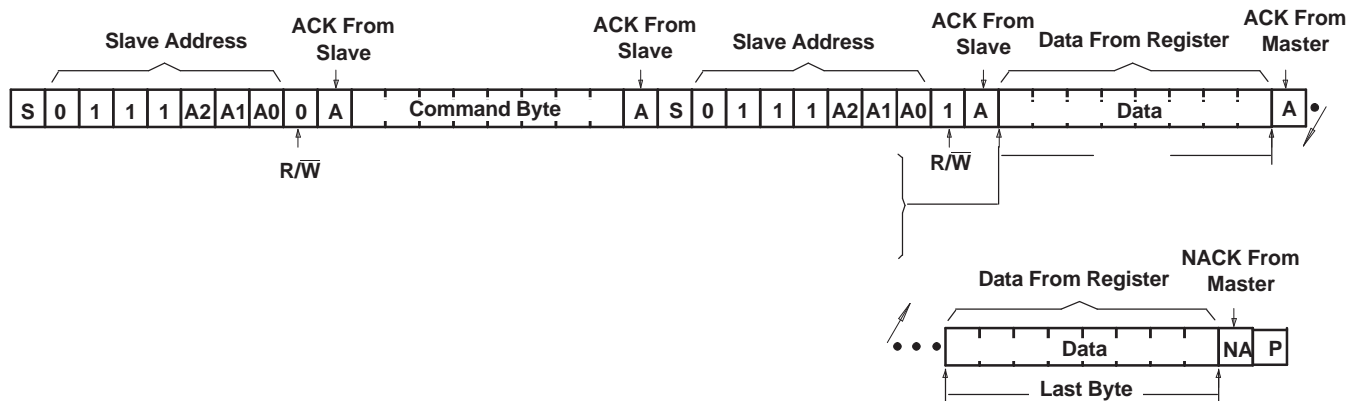
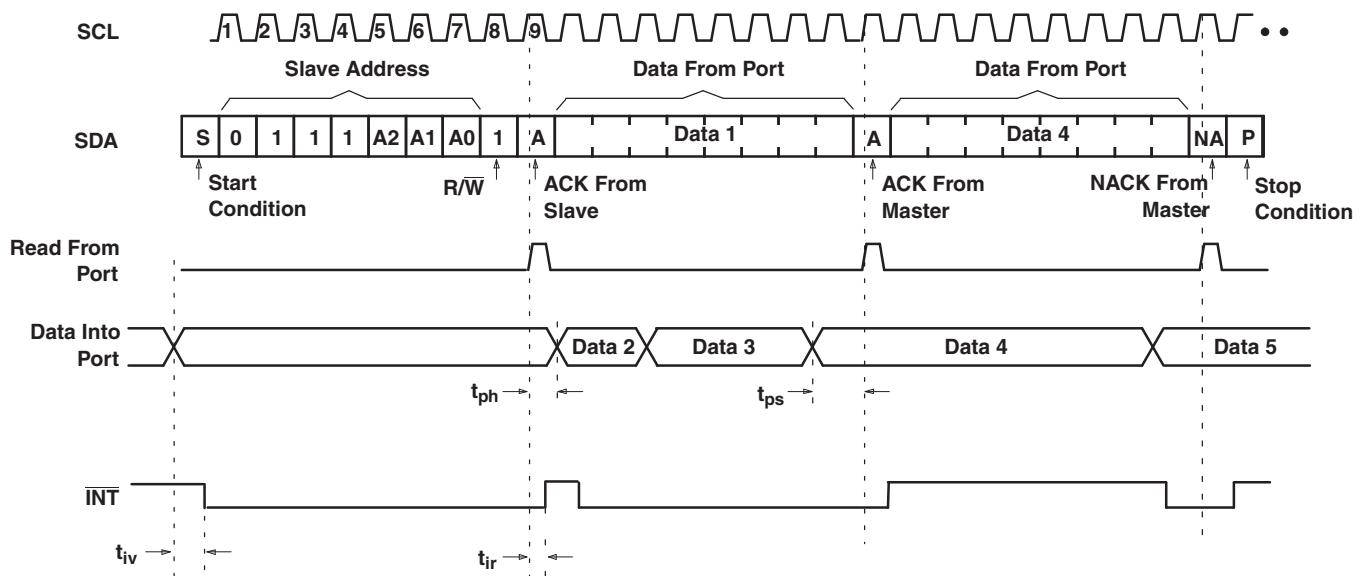


Figure 25. Write To Configuration Or Polarity Inversion Registers

**8.3.2.4.2 Reads**

The bus master first must send the PCA9554A address with the least significant bit (LSB) set to a logic 0 (see [Figure 22](#) for device address). The command byte is sent after the address and determines which register is accessed. After a restart, the device address is sent again, but this time the LSB is set to a logic 1. Data from the register defined by the command byte then is sent by the PCA9554A (see [Figure 26](#) and [Figure 27](#)). After a restart, the value of the register defined by the command byte matches the register being accessed when the restart occurred. Data is clocked into the register on the rising edge of the ACK clock pulse. There is no limitation on the number of data bytes received in one read transmission, but when the final byte is received, the bus master must not acknowledge the data.


**Figure 26. Read From Register**


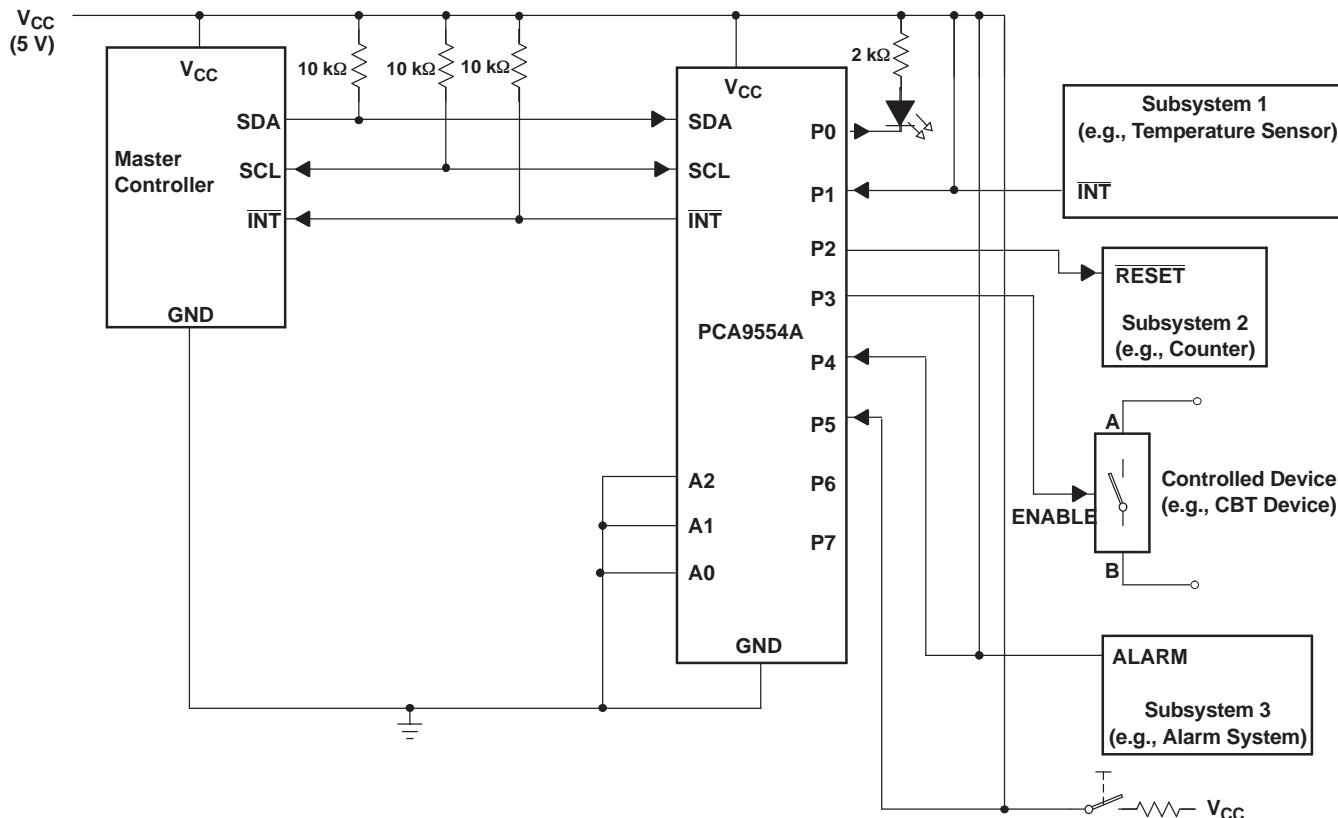
- This figure assumes the command byte has previously been programmed with 00h.
- Transfer of data can be stopped at any moment by a Stop condition.
- This figure eliminates the command byte transfer, a restart, and slave address call between the initial slave address call and actual data transfer from the P port. See [Figure 26](#) for these details.

**Figure 27. Read From Input Port Register**

## 9 Application And Implementation

### 9.1 Typical Application

Figure 28 shows an application in which the PCA9554A can be used.



- A. Device address is configured as 0111000 for this example.
- B. P0, P2, and P3 are configured as outputs.
- C. P1, P4, and P5 are configured as inputs.
- D. P6 and P7 are not used and have internal 100-kΩ pullup resistors to protect them from floating.

**Figure 28. Typical Application**

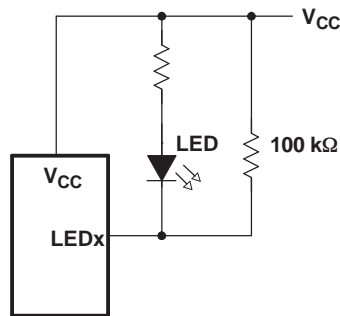
## Typical Application (continued)

### 9.1.1 Detailed Design Procedure

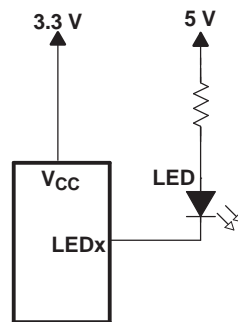
#### 9.1.1.1 Minimizing $I_{CC}$ When I/Os Control Leds

When the I/Os are used to control LEDs, they are normally connected to  $V_{CC}$  through a resistor as shown in Figure 28. Because the LED acts as a diode, when the LED is off, the I/O  $V_{IN}$  is about 1.2 V less than  $V_{CC}$ . The supply current,  $I_{CC}$ , increases as  $V_{IN}$  becomes lower than  $V_{CC}$  and is specified as  $\Delta I_{CC}$  in *Electrical Characteristics*.

For battery-powered applications, it is essential that the voltage of I/O pins is greater than or equal to  $V_{CC}$  when the LED is off to minimize current consumption. Figure 29 shows a high-value resistor in parallel with the LED. Figure 30 shows  $V_{CC}$  less than the LED supply voltage by at least 1.2 V. Both of these methods maintain the I/O  $V_{IN}$  at or above  $V_{CC}$  and prevents additional supply-current consumption when the LED is off.



**Figure 29. High-Value Resistor In Parallel With The Led**

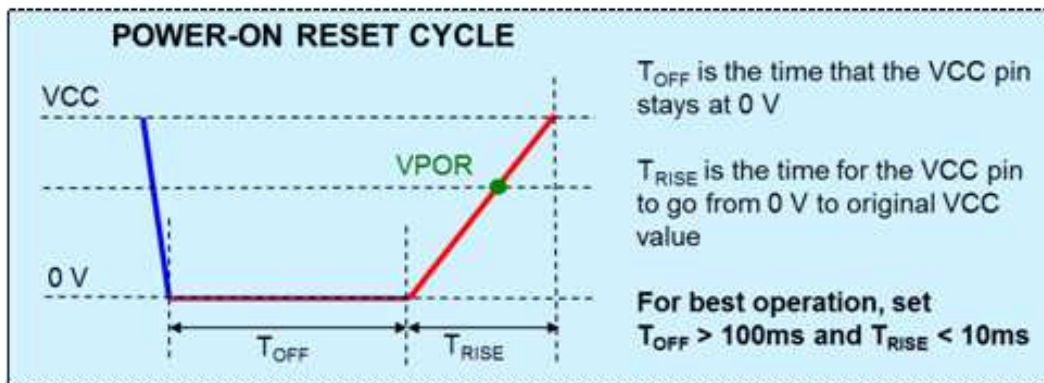


**Figure 30. Device Supplied By A Lower Voltage**

## 10 Power Supply Recommendations

### 10.1 Power-On Reset Errata

A power-on reset condition can be missed if the VCC ramps are outside specification listed below.



#### System Impact

If ramp conditions are outside timing allowances above, POR condition can be missed, causing the device to lock up.

## 11 Device and Documentation Support

### 11.1 Trademarks

All trademarks are the property of their respective owners.

### 11.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.3 Glossary

[SLYZ022](#) — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PCA9554ADB	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PD554A	<a href="#">Samples</a>
PCA9554ADBQR	NRND	SSOP	DBQ	16		TBD	Call TI	Call TI	-40 to 85		
PCA9554ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PD554A	<a href="#">Samples</a>
PCA9554ADGV	NRND	TVSOP	DGV	16		TBD	Call TI	Call TI	-40 to 85		
PCA9554ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PD554A	<a href="#">Samples</a>
PCA9554ADW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCA9554A	<a href="#">Samples</a>
PCA9554ADWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCA9554A	<a href="#">Samples</a>
PCA9554APW	NRND	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PD554A	
PCA9554APWR	NRND	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PD554A	
PCA9554APWRG4	NRND	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PD554A	
PCA9554ARGTR	ACTIVE	VQFN	RGT	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZVH	<a href="#">Samples</a>
PCA9554ARGVR	ACTIVE	VQFN	RGV	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	PD554A	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PCA9554ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
PCA9554ADWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
PCA9554APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
PCA9554ARGTR	VQFN	RGT	16	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
PCA9554ARGVR	VQFN	RGV	16	2500	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PCA9554ADGVR	TVSOP	DGV	16	2000	367.0	367.0	35.0
PCA9554ADWR	SOIC	DW	16	2000	350.0	350.0	43.0
PCA9554APWR	TSSOP	PW	16	2000	367.0	367.0	35.0
PCA9554ARGTR	VQFN	RGT	16	3000	367.0	367.0	35.0
PCA9554ARGVR	VQFN	RGV	16	2500	367.0	367.0	35.0

## GENERIC PACKAGE VIEW

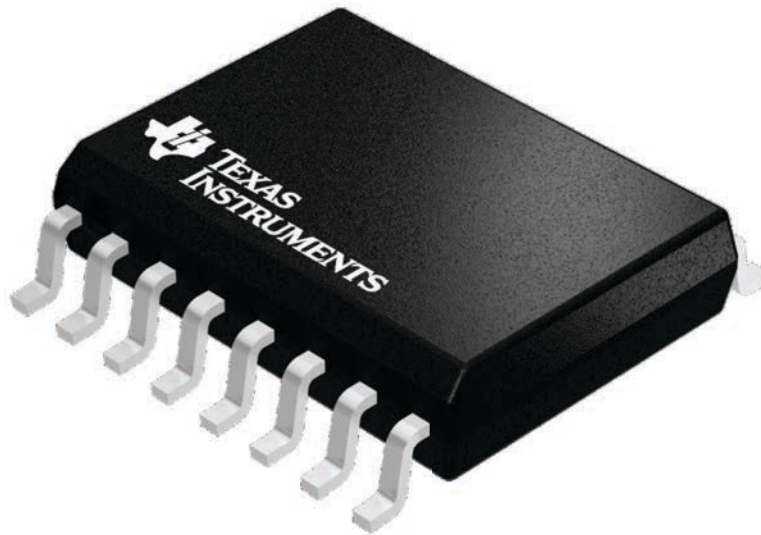
**DW 16**

**SOIC - 2.65 mm max height**

7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



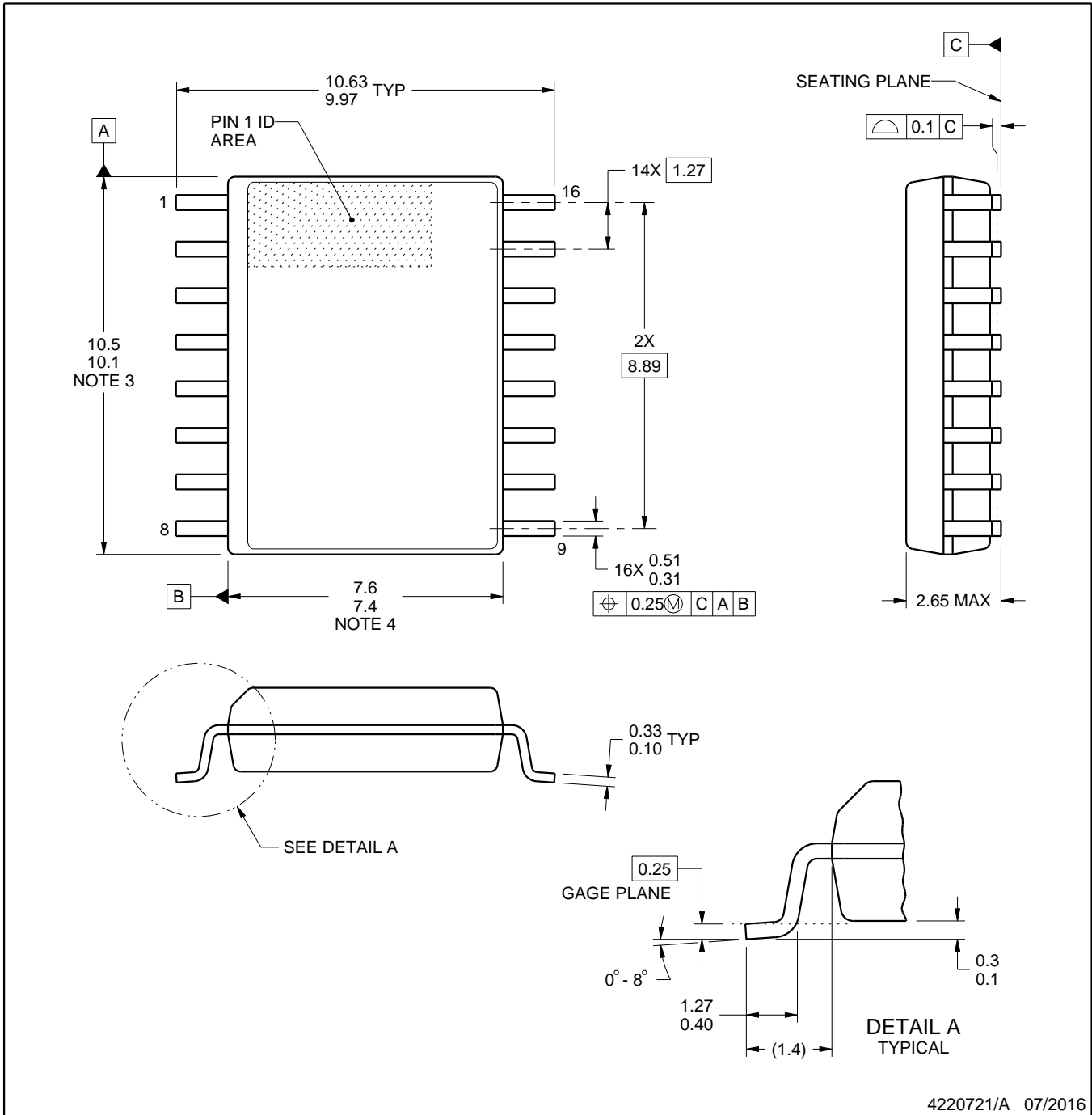
4224780/A



# DW0016A

# PACKAGE OUTLINE SOIC - 2.65 mm max height

SOIC



4220721/A 07/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0016A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:7X



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

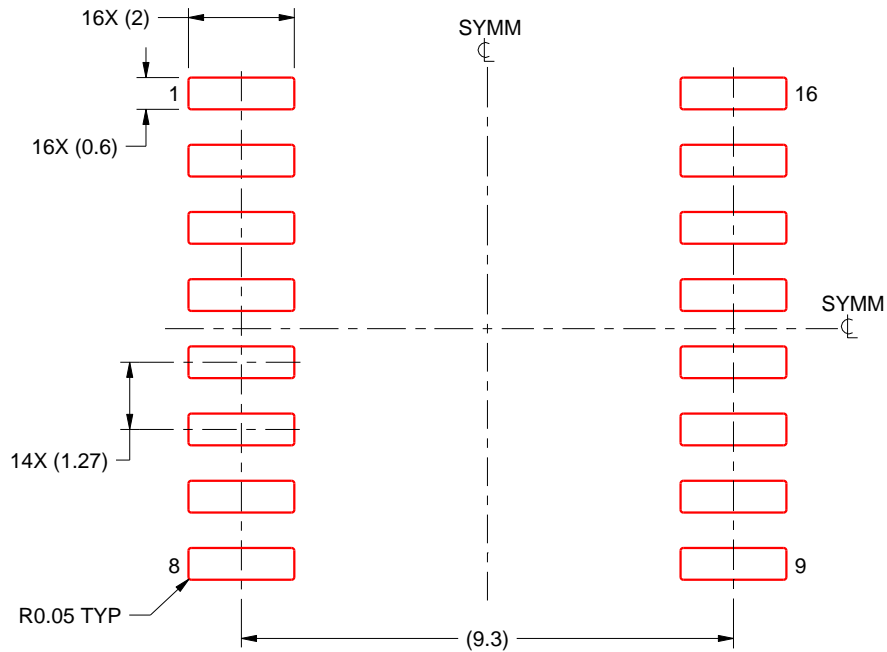
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0016A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:7X

4220721/A 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

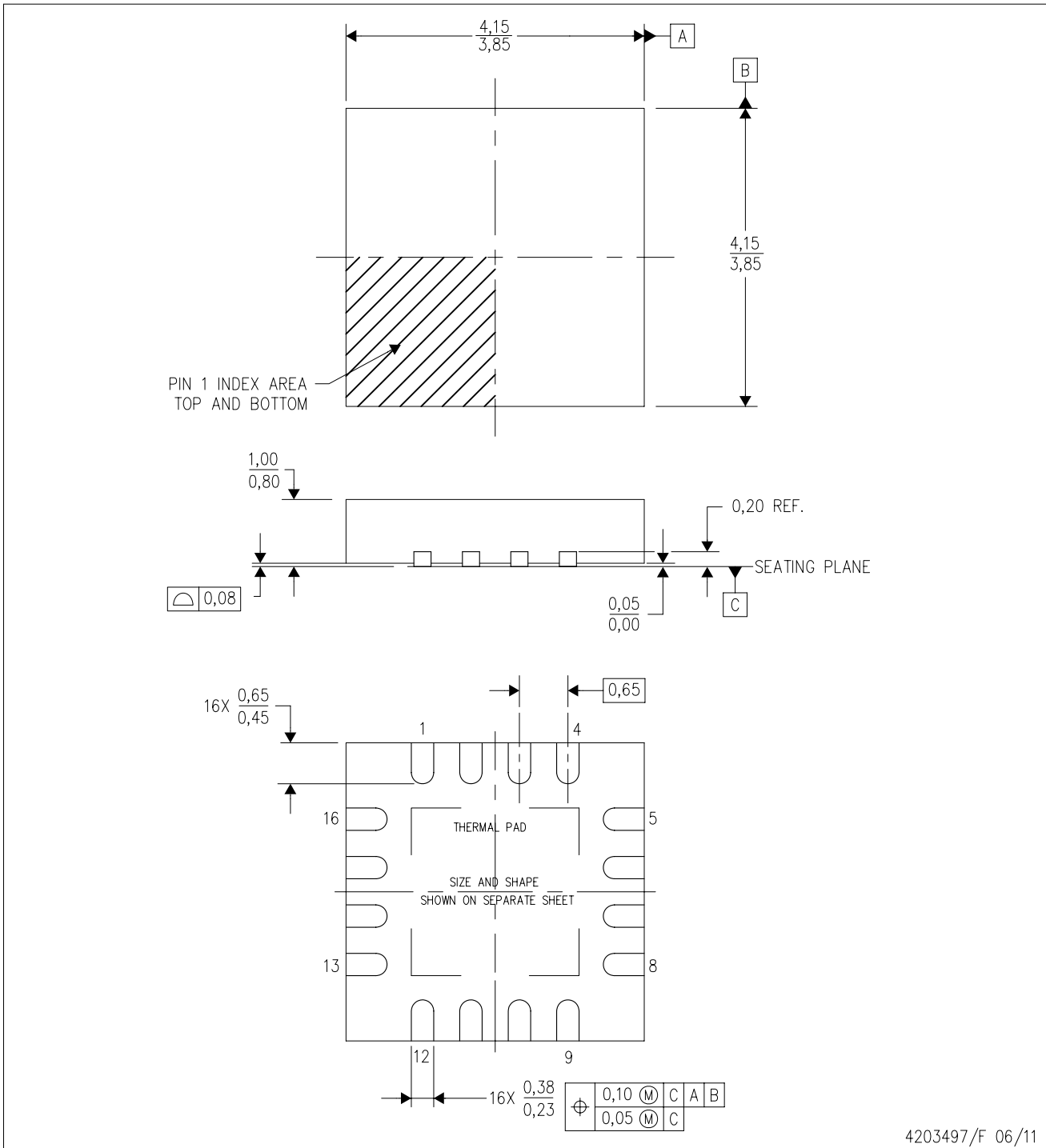
28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

RGV (S-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4203497/F 06/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Quad Flatpack, No-leads (QFN) package configuration.
  - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - F. Falls within JEDEC MO-220.

# THERMAL PAD MECHANICAL DATA

RGV (S-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206351-2/L 05/13

NOTE: All linear dimensions are in millimeters

RGV (S-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



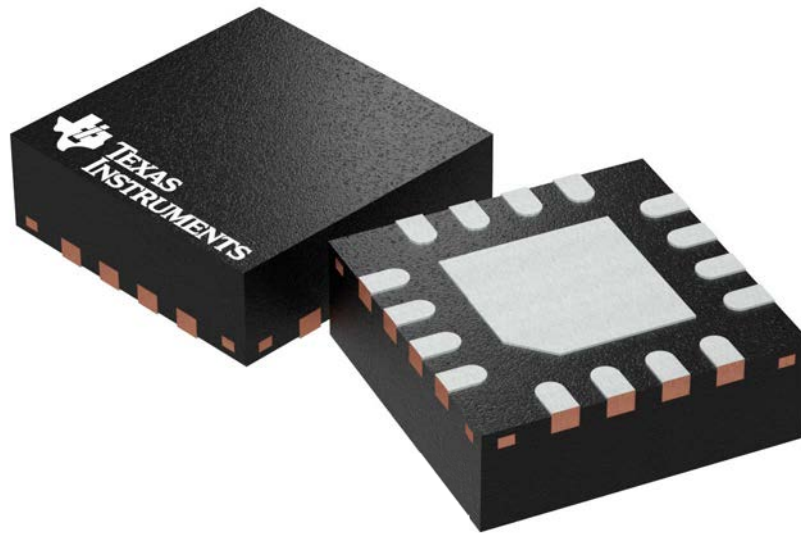
- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Publication IPC-7351 is recommended for alternate designs.  
 D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.  
 E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.  
 F. Customers should contact their board fabrication site for solder mask tolerances.

**RGT 16**

**GENERIC PACKAGE VIEW**

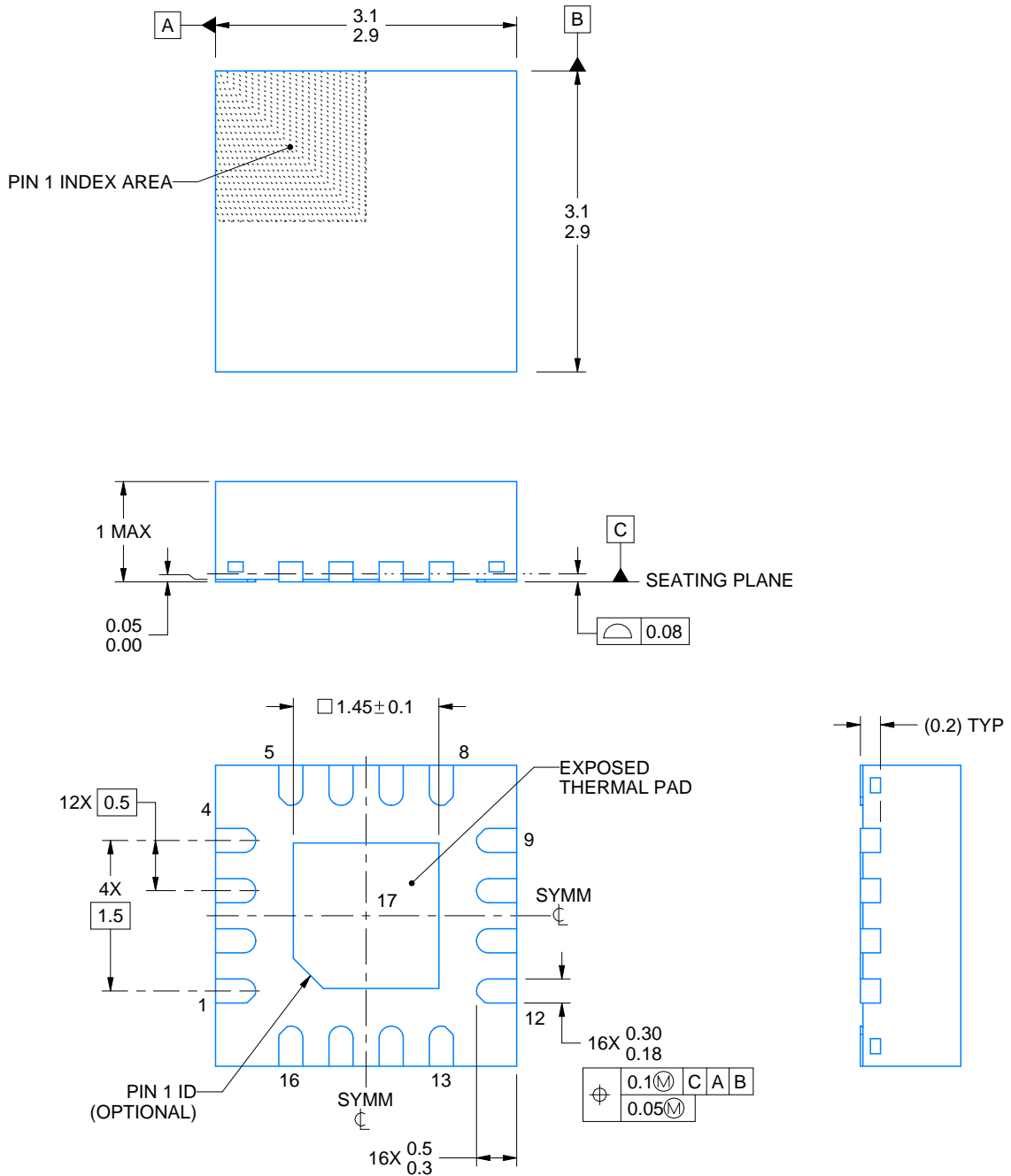
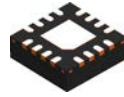
**VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4203495/1



4219032/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Reference JEDEC registration MO-220

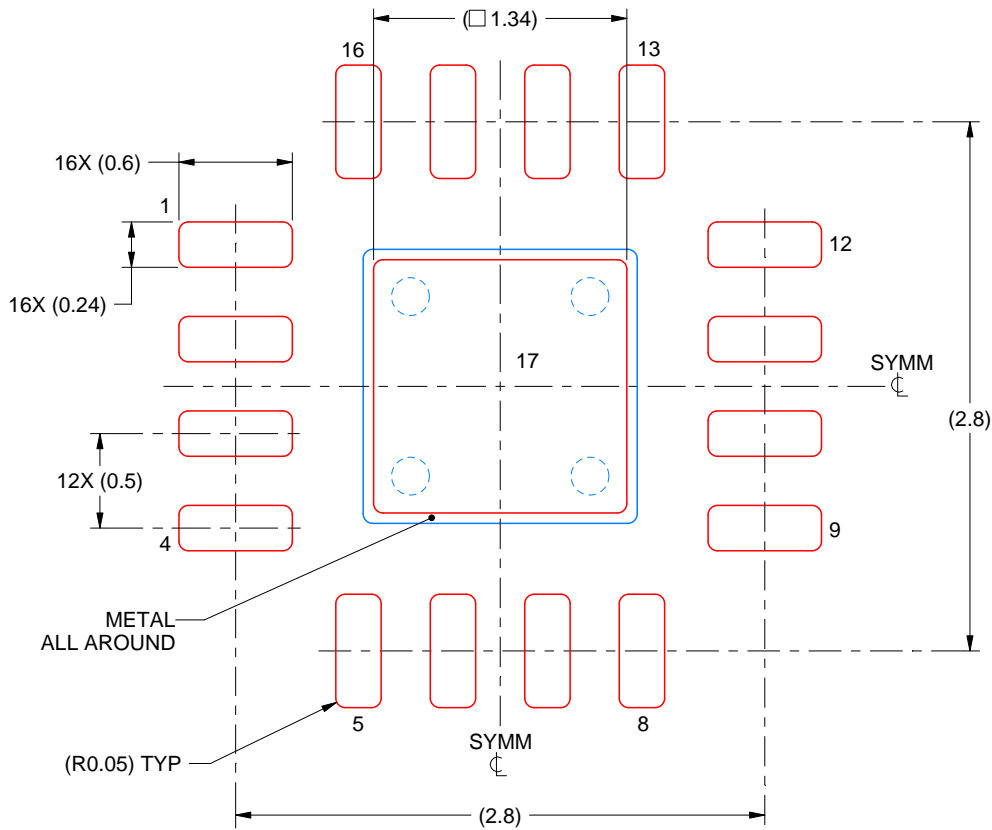


# EXAMPLE STENCIL DESIGN

RGT0016A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



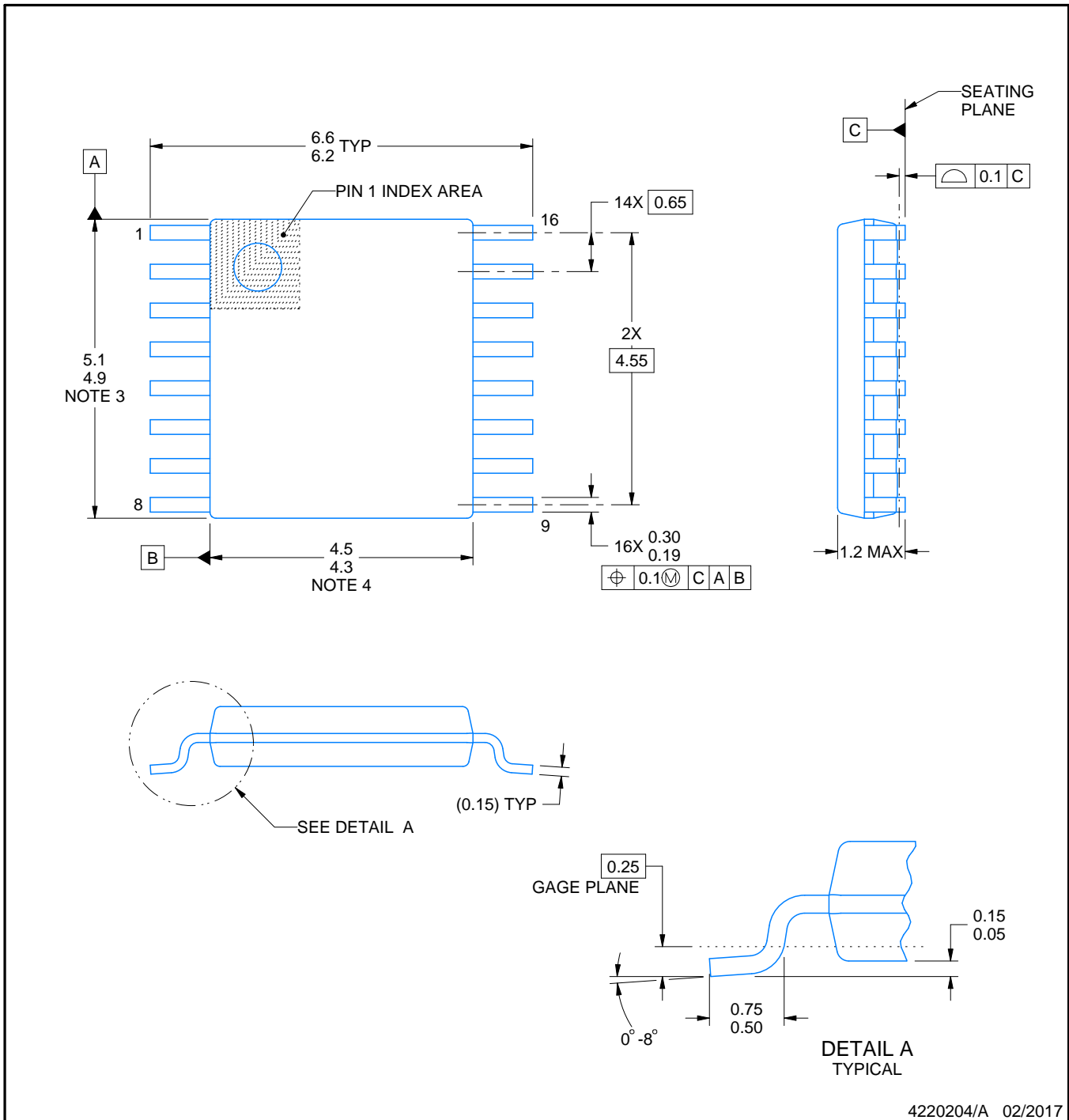
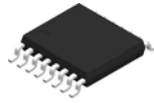
**SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 17:  
86% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:25X

4219032/A 02/2017

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



4220204/A 02/2017

NOTES:

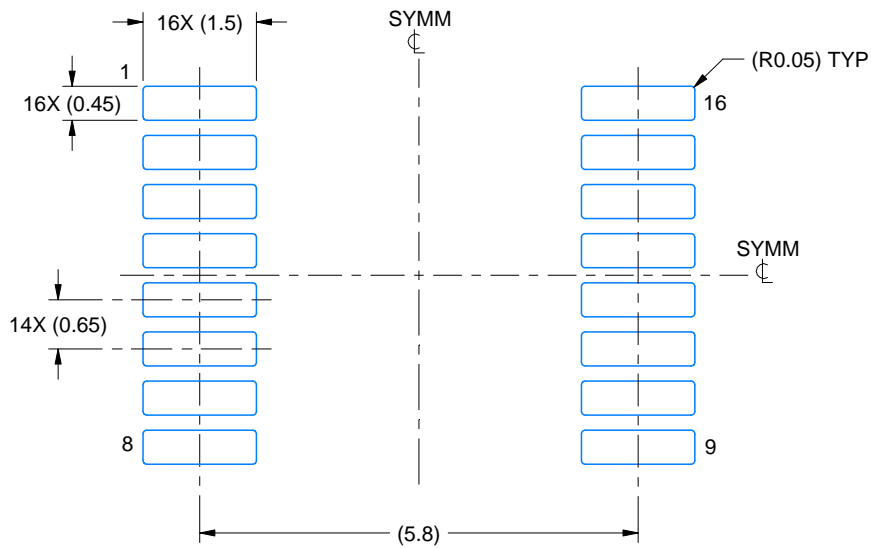
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220204/A 02/2017

NOTES: (continued)

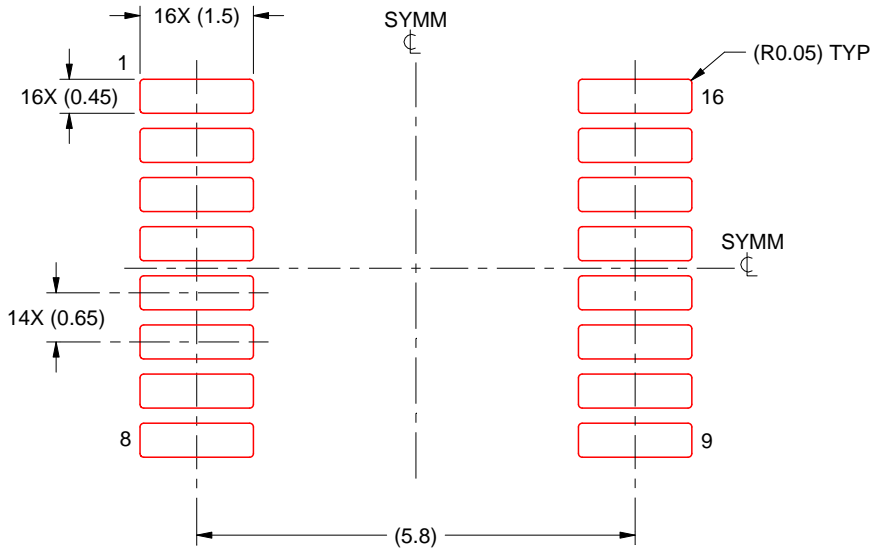
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on [ti.com](http://ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2019, Texas Instruments Incorporated

## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View PCA9554ARGVR on WIN SOURCE](#)

 [Texas Instruments](#) Information

## Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management